

40V N-Channel Enhancement Mode MOSFET

Description

The AP2N04I uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 40V$ $I_D = 2A$

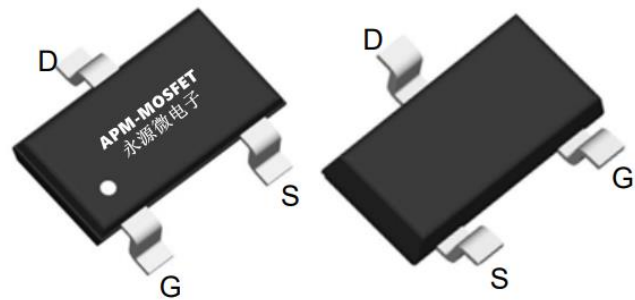
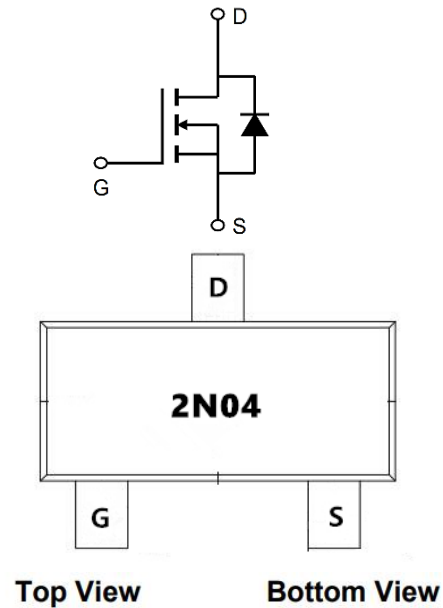
$R_{DS(ON)} < 180m\Omega$ @ $V_{GS}=10V$ (Type: **128mΩ**)

Application

Wireless charging

Boost driver

LED



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP2N04I	SOT23L	2N04	3000

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	2	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	1.9	A
I_{DM}	Pulsed Drain Current ²	6	A
EAS	Single Pulse Avalanche Energy ³	1.5	mJ
$P_D@T_A=25^\circ C$	Total Power Dissipation ⁴	1.67	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	125	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	60	$^\circ C/W$

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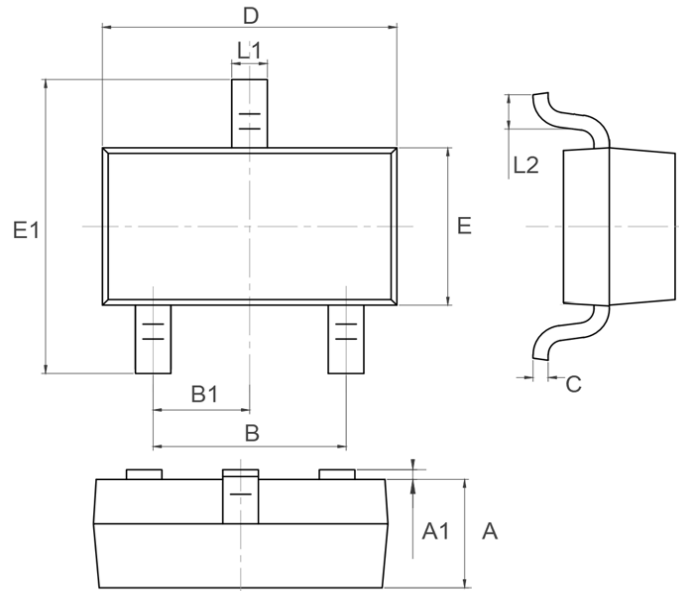
Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	40	44	---	V
$\Delta BVDSS/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.032	---	V/ $^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=4A$	---	128	180	m Ω
		$V_{GS}=4.5V, I_D=3A$	---	145	200	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	1.5	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4.5	---	mV/ $^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=32V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	uA
		$V_{DS}=32V, V_{GS}=0V, T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=5V, I_D=4A$	---	8	---	S
Rg	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	2.4	4.8	Ω
Qg	Total Gate Charge (4.5V)	$V_{DS}=20V, V_{GS}=4.5V, I_D=3A$	---	2.1	---	nC
Qgs	Gate-Source Charge		---	0.54	---	
Qgd	Gate-Drain Charge		---	0.84	---	
Td(on)	Turn-On Delay Time	$V_{DD}=20V, V_{GS}=10V, R_G=3.3\Omega, I_D=1A$	---	2.8	---	ns
Tr	Rise Time		---	1.1	---	
Td(off)	Turn-Off Delay Time		---	14	---	
Tf	Fall Time		---	1.1	---	
Ciss	Input Capacitance	$V_{DS}=20V, V_{GS}=0V, f=1\text{MHz}$	---	152	---	pF
Coss	Output Capacitance		---	21	---	
Crss	Reverse Transfer Capacitance		---	18	---	
IS	Continuous Source Current ^{1,4}	$V_G=V_D=0V, \text{Force Current}$	---	---	2.0	A
ISM	Pulsed Source Current ^{2,4}		---	---	6.0	A
VSD	Diode Forward Voltage ²	$V_{GS}=0V, I_S=1A, T_J=25^\circ\text{C}$	---	---	1.2	V

Note :

- 1、The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3、The power dissipation is limited by 150°C junction temperature
- 4、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Package Mechanical Data-SOT23L



Symbol	Dim in mm		
	Min	Typ	Max
A	0.9	1	1.1
A1	0	0.05	0.1
B	1.8	1.9	2
B1	0.95TYP		
C	0.08	0.115	0.15
D	2.8	2.9	3
E	1.2	1.3	1.4
E1	2.25	2.4	2.55
L1	0.3	0.4	0.5
L2	0.2	0.35	0.5

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Edition	Date	Change
REV1.0	2024/3/13	Initial release

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